Docket No.: K-0393

DECLARATION AND POWER OF ATTORNEY

| As a below named inventor, I hereby declar | are that: | |
|--|---|---|
| My residence, post office and citizenship a | are as stated below next to my name, | |
| names are listed below) of the subject mat | ter claimed and for which a patent is so | ow) or an original, first and joint inventor (if plural ought on the invention entitled METHOD OF NICATION SYSTEM, the specification of |
| [X] is attached hereto [] was filed on | on as Application (if app | Serial Noand was licable) |
| I hereby state that I have reviewed and amended by any amendment referred to ab | | identified specification, including the claims, as |
| I acknowledge the duty to disclose inform Code of Federal Regulations, Section 1.56 | | terial to patentability in accordance with Title 37, |
| certificate, or 365(a) of any PCT internat America, listed below and have also ide | tional application which designated at entified below, by checking the box, | any foreign application(s) for patent or inventor's least one country other than the United States of any foreign application for patent or inventor's t of the application on which priority is claimed. |
| Prior Foreign Application(s): Number | Country | Foreign Filing Date <u>Month/Day/Year</u> |
| P2001-8526 | KOREA | February 20, 2001 |
| I hereby claim the benefit under 35 U.S.C. Application Number(s): | .119(e) of any United States provisiona Filing Date(Month/Day/Y | |
| designating the United States of America, not disclosed in the prior United States or 112, I acknowledge the duty to disclose i available between the filing date of the prior the prior of | listed below and, insofar as the subject PCT international application in the mainformation which is material to paten | n(s), or 365(c) of any PCT international application it matter of each of the claims of this application is anner provided by the first paragraph of 35 U. S. C. tability as defined in 37 CFR 1.56 which became international filing date of this application. |
| Prior U.S. Application or PCT Parent Number | Filing Date(Month/Day/Year) | Parent Patent Number (if applicable) |
| | | |

belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that

such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vasquez, Registration No. 38,647; Stuart I. Smith, Registration No. 42,159; Carol L. Druzbick, Registration No. 40,287; Anthony H.Nourse, Registration No. 46,121; and Margaret A. Burke, Registration No. 34,474, all of

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| with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademar Office connected therewith, and all future correspondence should be addressed to them. |
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